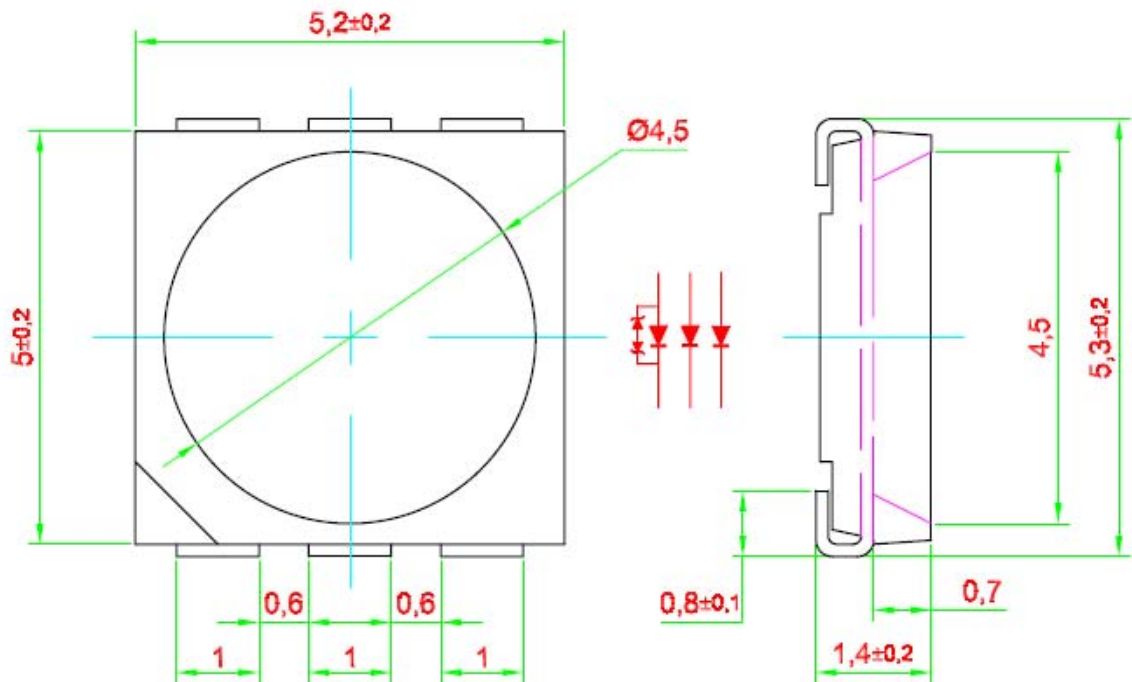


Engineering reference data are not verified. The specifications are subject to change without notice.

Maxi DomiLED White: DBWW-DJG

- Super high brightness surface mount LED.
- Large light emitting window of 4.5mm diameter.
- 120° viewing angle.
- Compact package outline (LxW) of 5.3 x 5.2 x 1.4 mm.
- Compatible to IR reflow soldering.

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Material

	Material
Lead-frame.	Cu Alloy With Ag Plating.
Package.	High Temperature Resistant Plastic, PPA.
Encapsulant	Silicone Resin.
Soldering Leads.	Sn Plating.

Note: This product is Pb free.

Absolute Maximum Ratings

	Maximum Value	Unit
DC forward current. ^{*1}	20	mA
Peak pulse current. ^{*1} ($t_p \leq 10 \mu s$, Duty cycle = 0.1)	100	mA
Reverse voltage. ^{*1}	Not designed for reverse bias	V
LED junction temperature. ^{*1}	125	°C
Operating temperature.	-40 ... +100	°C
Storage temperature.	-40 ... +100	°C
ESD Threshold (HBM)	1000	V

*1 Rating is based on individual chip.

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Optical Characteristics at Tj=25°C.

Part Number	Intensity @ If=20mA (mcd) / chip			Viewing Angle
	Min	Typ.	Max	
DBWWW-DJG-Z4Z5-R	5,000	6,000	7,000	120

IV Bin	Intensity @ If = 20mA (mcd)	
	Min	Max
Z4	5,000	6,000
Z5	6,000	7,000

1. Luminous intensity is measured with an accuracy of ±11%.
2. Wavelength binning is carried for all units as per the wavelength-binning table. Only one wavelength group is allowed for each reel.

Electrical Characteristics at Tj=25°C.

Part Number	Vf @ If = 20mA		
	Min. (V)	Typ. (V)	Max.(V)
DBWWW-DJG	2.9	3.2	3.5

Forward voltages are tested using a current pulse of 1 ms and has an accuracy of ± 0.1V.

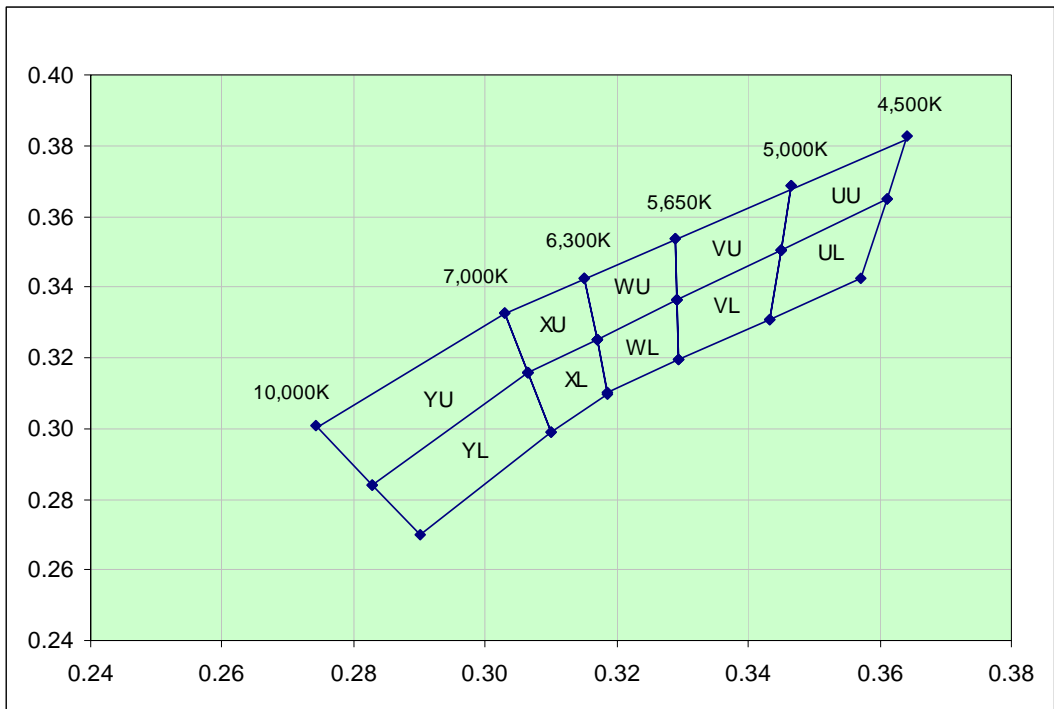
Vf Binning

Vf Bin @ 20mA	Forward voltage (V)
V1	2.90 ... 3.00
V2	3.00 ... 3.10
V3	3.10 ... 3.20
V4	3.20 ... 3.30
V5	3.30 ... 3.40
V6	3.40 ... 3.50

Forward voltage, Vf is measured with an accuracy of ±0.1 V.

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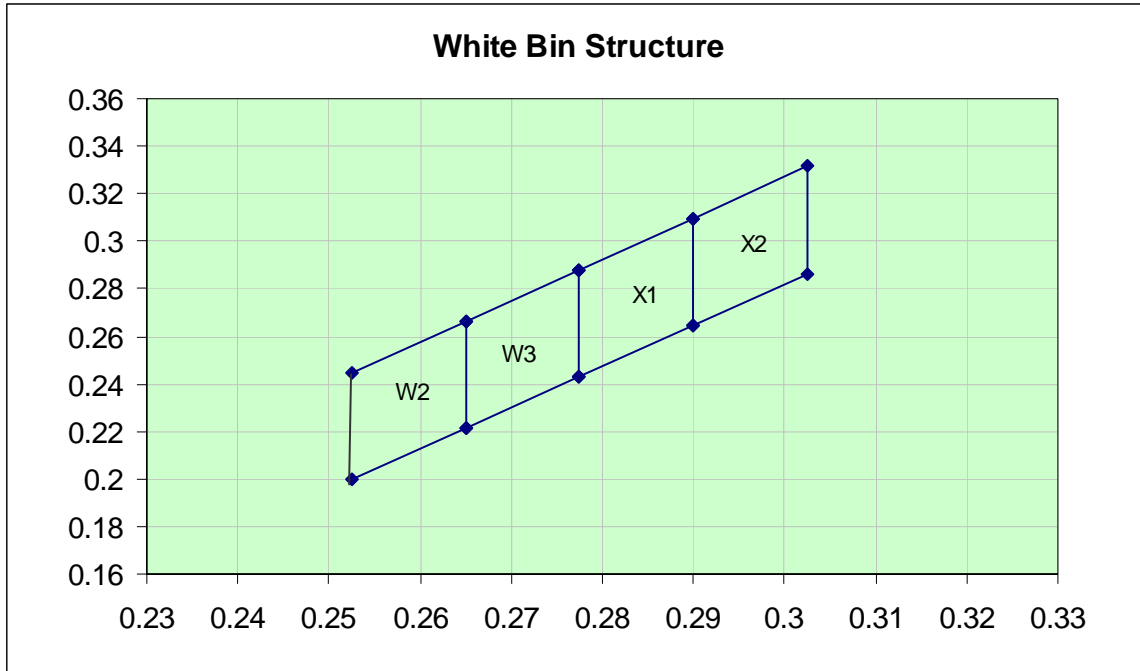
Color Bin



Chromaticity coordinate groups are measured with an accuracy of ± 0.01 .

Bin		1	2	3	4
YU	Cx	0.274	0.283	0.307	0.303
	Cy	0.301	0.284	0.316	0.333
YL	Cx	0.283	0.290	0.310	0.307
	Cy	0.284	0.270	0.299	0.316
XU	Cx	0.303	0.307	0.317	0.315
	Cy	0.333	0.316	0.325	0.343
XL	Cx	0.307	0.310	0.319	0.317
	Cy	0.316	0.299	0.310	0.325
WU	Cx	0.315	0.317	0.329	0.329
	Cy	0.343	0.325	0.336	0.354
WL	Cx	0.317	0.319	0.329	0.329
	Cy	0.325	0.310	0.319	0.336
VU	Cx	0.329	0.329	0.345	0.347
	Cy	0.354	0.336	0.350	0.368
VL	Cx	0.329	0.329	0.343	0.345
	Cy	0.336	0.319	0.331	0.350
UU	Cx	0.347	0.345	0.361	0.364
	Cy	0.368	0.350	0.365	0.383
UL	Cx	0.345	0.343	0.357	0.361
	Cy	0.350	0.331	0.343	0.365

Engineering reference data are not verified. The specifications are subject to change without notice.

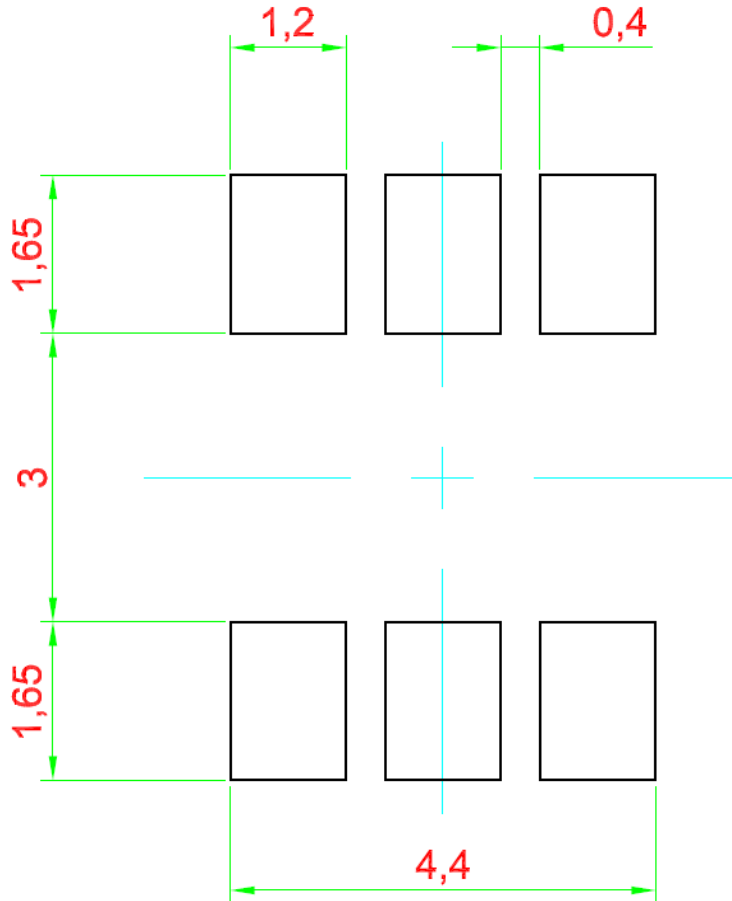


Chromaticity coordinate groups are measured with an accuracy of ± 0.01 .

W2	0.2525	0.2650	0.2650	0.2525
	0.1998	0.2215	0.2665	0.2448
W3	0.2650	0.2775	0.2775	0.2650
	0.2215	0.2431	0.2881	0.2665
X1	0.2775	0.2900	0.2900	0.2775
	0.2431	0.2648	0.3098	0.2881
X2	0.2900	0.3025	0.3025	0.2900
	0.2648	0.2864	0.3314	0.3098

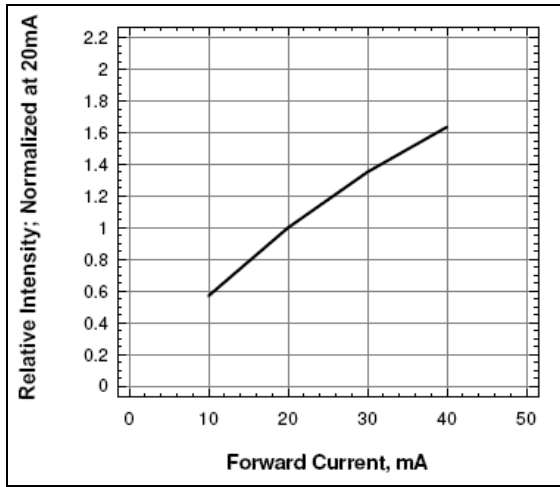
Engineering reference data are not verified. The specifications are subject to change without notice.

Solder Pad Design.

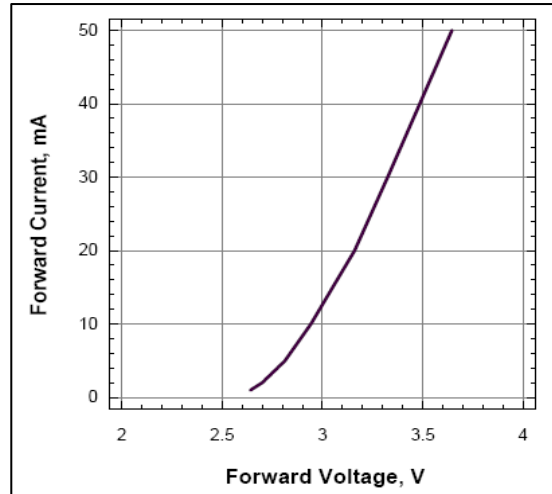


Engineering reference data are not verified. The specifications are subject to change without notice.

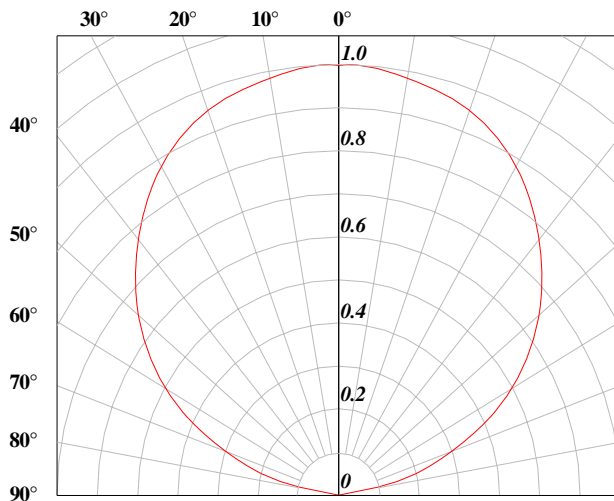
Relative intensity vs. forward current



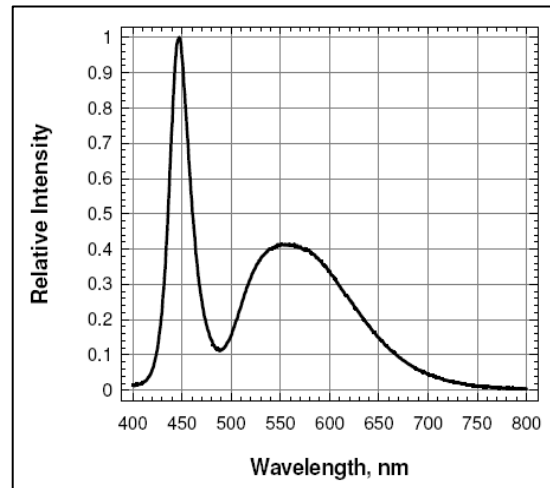
Forward voltage vs. forward current



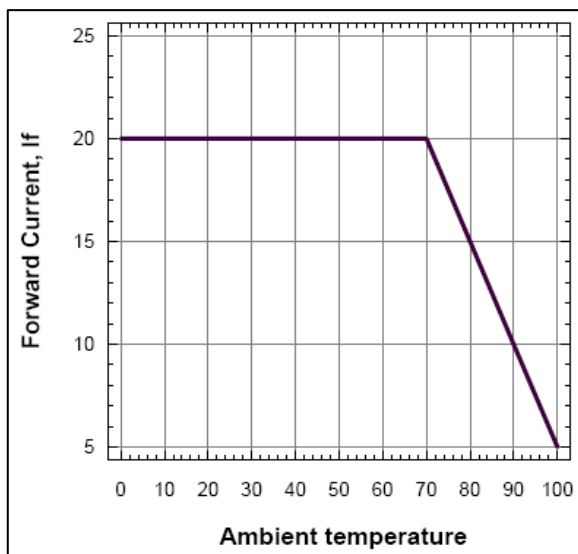
Radiation pattern.



Color Spectrum



Maximum forward current vs. temperature

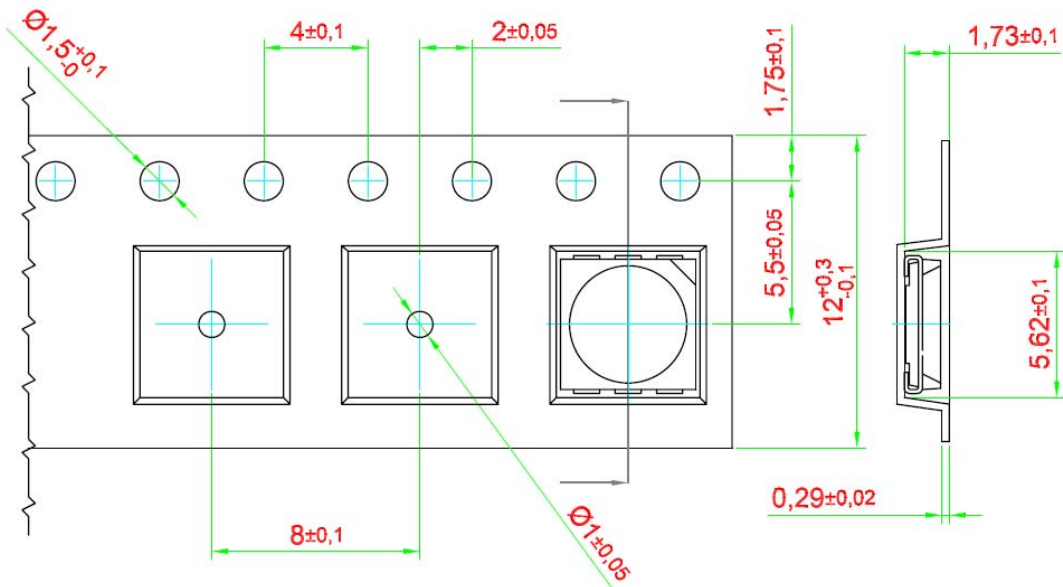


Engineering reference data are not verified. The specifications are subject to change without notice.

Taping And Orientation.

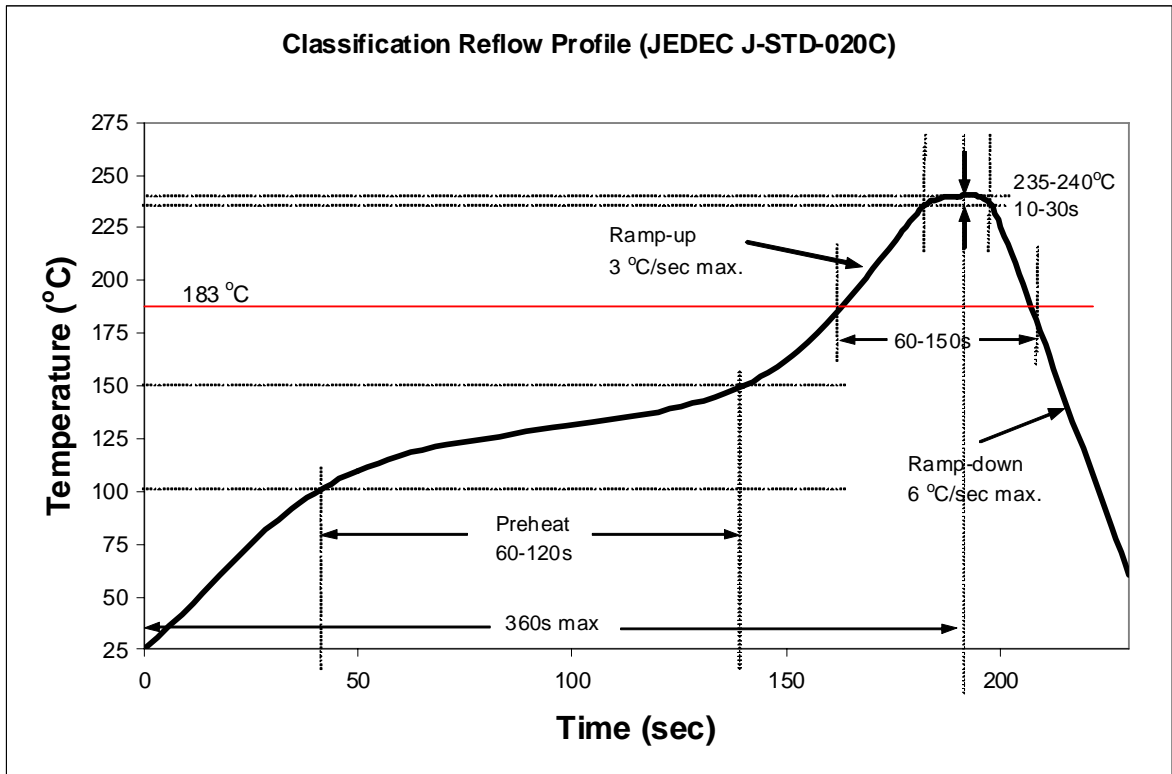
Reels come in quantity of 1000 units.

Reel diameters are 180 mm.

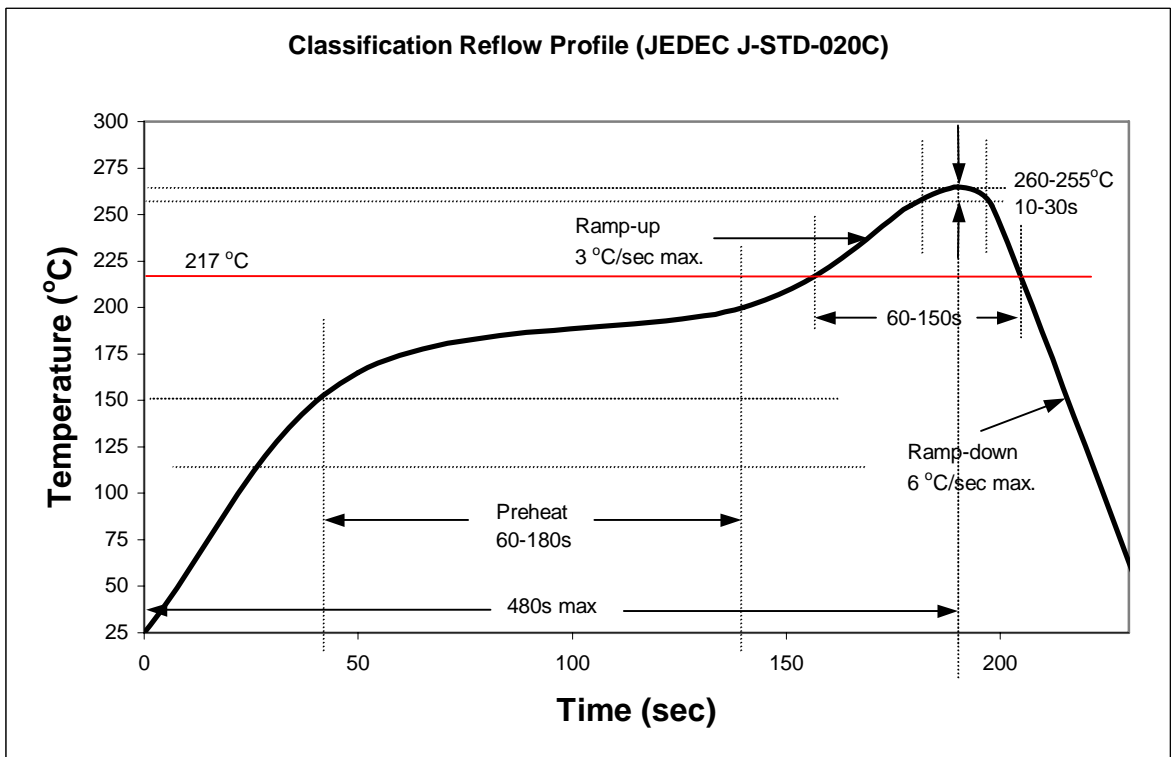


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Recommended Sn-Pb IR-Reflow Soldering Profile.



Recommended Pb Free IR-Reflow Soldering Profile.



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